1A, 100V - 200V Ultra Fast Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Planar technology
- Low power loss, high efficiency
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- High frequency switching
- DC/DC
- Snubber

MECHANICAL DATA

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.027g (approximately)

KEY PARAMETERS				
PARAMETER VALUE UNIT				
١ _F	1	А		
V _{RRM}	100 - 200	V		
I _{FSM}	45	А		
T _{J MAX}	175	°C		
Package	SOD-128			
Configuration	Single die			









ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)					
PARAMETER		SYMBOL	PU1BFSH	PU1DFSH	UNIT
Marking code on the device			PU1BFS	PU1DFS	
Repetitive peak reverse voltage		V _{RRM}	100	200	V
Reverse voltage, total rms value		V _{R(RMS)}	70	140	V
Forward current		I _F	1		Α
Surge peak forward current single half t = 8.3ms		1	45		
sine-wave superimposed on rated load	t = 1.0ms	I _{FSM}	100		A
Junction temperature		TJ	-55 to +175		°C
Storage temperature		T _{STG}	-55 to +175		°C



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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	ТҮР	UNIT		
Junction-to-lead thermal resistance	R _{ƏJL}	17	°C/W		
Junction-to-ambient thermal resistance	R _{ØJA}	75	°C/W		
Junction-to-case thermal resistance	R _{eJC}	20	°C/W		

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ($T_A = 25^{\circ}C$ unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage ⁽¹⁾	$I_F = 0.5A, T_J = 25^{\circ}C$		0.79	-	V
	$I_F = 1.0A, T_J = 25^{\circ}C$		0.84	0.93	V
	$I_F = 0.5A, T_J = 125^{\circ}C$	V _F	0.64	-	V
	$I_F = 1.0A, T_J = 125^{\circ}C$	-	0.70	-	V
Reverse current @ rated $V_R^{(2)}$	$T_J = 25^{\circ}C$	I _R	-	2	μA
	$T_J = 125^{\circ}C$		-	10	μA
Junction capacitance	1MHz, V _R = 4.0V	CJ	19	-	pF
Doverse recovery time	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$	4	-	25	ns
Reverse recovery time	$I_F = 1.0A$, di/dt = 50A/µs, $V_R = 30V$	t _{rr}	34	-	
Reverse recovery current		I _{RM}	3.4	-	А
Reverse recovery charge	$I_F = 1.0A$, di/dt = 200A/µs, $V_R = 100V$	Q _{rr}	27	-	nC
Reverse recovery time]	t _{rr}	19	-	ns

Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING	
PU1xFSH	SOD-128	14,000/ Tape & Reel	

Notes:

1. "x" defines voltage from 100V(PU1BFSH) to 200V(PU1DFSH)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

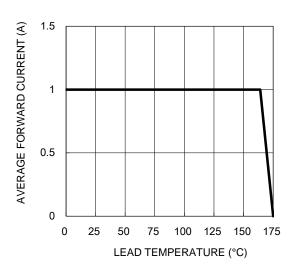
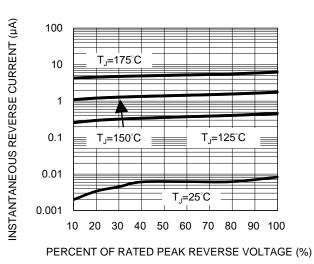


Fig.1 Forward Current Derating Curve

Fig.3 Typical Reverse Characteristics



TRANSIENT THERMAL IMPEDANCE (°C/W)

0.001

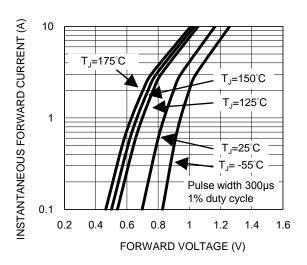
0.0001

0.000001 0.00001

100 CAPACITANCE (pF) 10 f=1.0MHz Vsig=50mVp-p 1 10 100 1 **REVERSE VOLTAGE (V)**

Fig.2 Typical Junction Capacitance

Fig.4 Typical Forward Characteristics

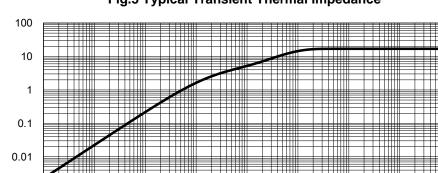


10

100

++++

1



0.0001

0.001

Fig.5 Typical Transient Thermal Impedance

0.01 PULSE DURATION (s)

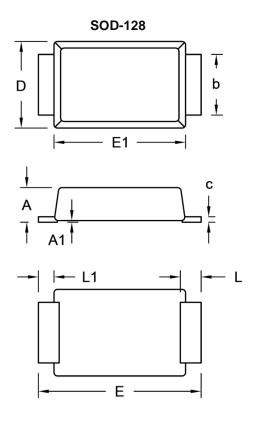
0.1



PU1BFSH – PU1DFSH

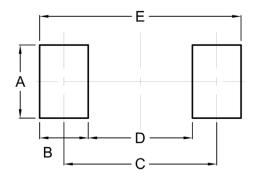
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PACKAGE OUTLINE DIMENSIONS



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	0.90	1.10	0.035	0.043
A1	0.00	0.10	0.000	0.004
b	1.60	1.90	0.063	0.075
с	0.10	0.22	0.004	0.009
D	2.30	2.70	0.091	0.106
E	4.40	5.00	0.173	0.197
E1	3.60	4.00	0.142	0.157
L	0.40	0.80	0.016	0.031
L1	0.30	0.60	0.012	0.024

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

MARKING DIAGRAM



P/N	= Marking	Code
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YW = Date Code

F = Factory Code



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